

Title (en)  
METHOD FOR ASSEMBLING AND PACKAGING A HEATING DEVICE

Title (de)  
VERFAHREN ZUM MONTIEREN UND VERPACKEN EINER HEIZVORRICHTUNG

Title (fr)  
PROCÉDÉ D'ASSEMBLAGE ET D'EMBALLAGE D'UN DISPOSITIF DE CHAUFFAGE

Publication  
**EP 4227234 A1 20230816 (EN)**

Application  
**EP 22156690 A 20220215**

Priority  
EP 22156690 A 20220215

Abstract (en)  
provide a method for assembling and packaging of a heating device, in particular an indoor hydraulic module of a heat pump or a boiler, wherein the method comprises the steps of providing a bottom base on a mounting surface, positioning a part of a hydraulic module of a heating device onto the bottom base, secure one or more casing elements to the part of the hydraulic module using a securing means to assemble the heating device, and positioning a cover over at least an upper part of the assembled heating device, wherein the bottom base and/or the cover is folded to create a box around the assembled heating device, and wherein the bottom base and the cover are made of a recyclable, foldable, packaging material.

IPC 8 full level  
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• [X] US 2932438 A 19600412 - SMITH MAX M  
• [X] KR 20080002306 U 20080702  
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• [A] JP 2003237877 A 20030827 - FUJITSU GENERAL LTD  
• [A] WO 2016181485 A1 20161117 - MITSUBISHI ELECTRIC CORP [JP]  
• [A] KR 20080001444 U 20080530  
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BA ME

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KH MA MD TN

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